

**SPECIFICATIONS:**

**ELECTRICAL:**  
 RATED CURRENT: 5A  
 RATED VOLTAGE: 300VDC  
 WITHSTANDING VOLTAGE: 500VAC (rms) FOR 1 MIN  
 INSULATION RESISTANCE: > 1,000 mΩ at 500VDC  
 CONTACT RESISTANCE: 13mOhms MAX  
 DIELECTRIC STRENGTH: 1000VAC FOR 1 MIN  
 OPERATING TEMPERATURE: -55°C TO +105°C

**MATERIALS:**  
 SHELL: NICKEL PLATED STEEL  
 BRACKET: NICKEL PLATED STEEL  
 INSULATOR: NYLON 6T, UL 94V-0, BLACK  
 PROCESS TEMP: 260°C  
 INSULATOR: PATONE #322C, COLOR=Pc99  
 CONTACT: TIN PLATED PHOSPHOR BRONZE  
 GOLD FLASH MATING AREA  
 TIN PLATED SOLDER AREA

**Storage and Process Instructions:**

For parts exposed to greater than 60% RH, it is recommended parts be baked at 125°C for 3-5 hours prior to SMT reflow process. If unsure of RH exposure, it is recommend to bake at the above temperature and time prior to SMT reflow process.

RoHS COMPLIANT

UNITS = inch [mm]

DO NOT SCALE FROM DRAWING



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DRAWN:  
C. SMITH

DATE:  
04/14/2009

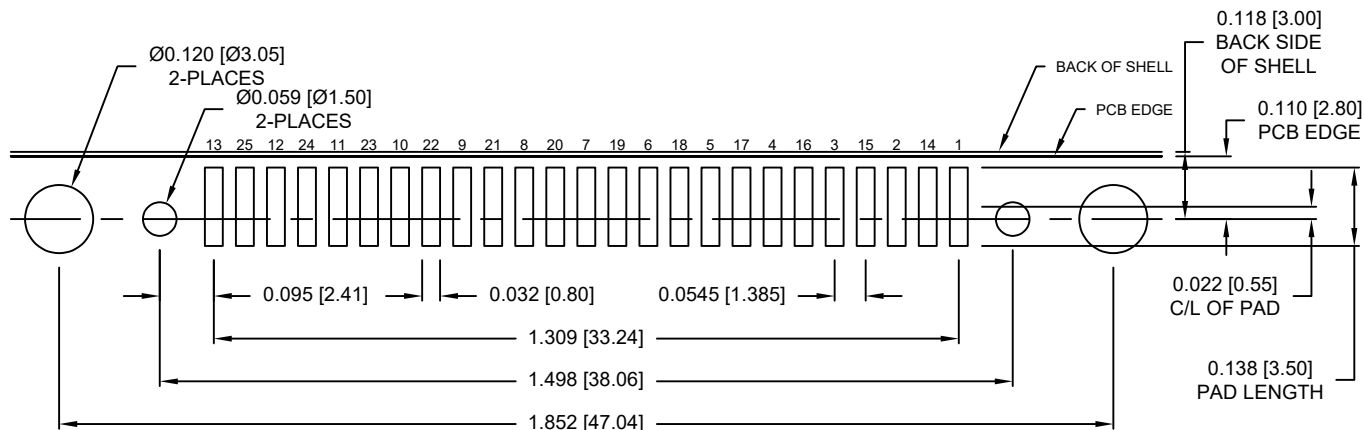
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SCALE:  
NTS

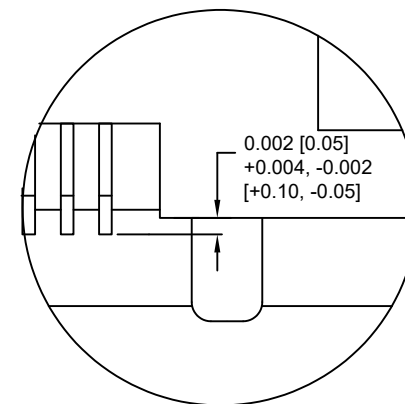
SHEET OF  
1 2

REV  
12

DWG NO. 190-025-163R001



RECOMMENDED PCB LAYOUT

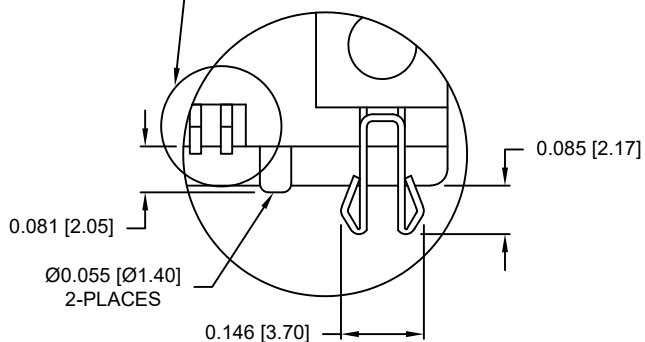


DETAIL "B"  
CONTACT COPLANARITY

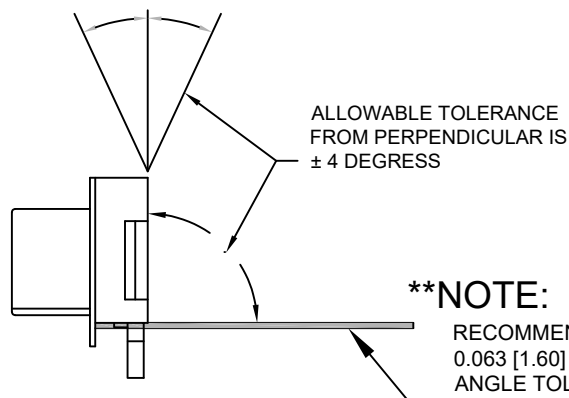
CONTACT ARRANGEMENT

13 25 12 24 11 23 10 22 9 21 8 20 7 19 6 18 5 17 4 16 3 15 2 14 1

SEE DETAIL "B"  
FOR CONTACT  
COPLANARITY



DETAIL "A"



**\*\*NOTE:**

RECOMMENDED PCB THICKNESS IS  
0.063 [1.60] ± 0.002 [0.05] TO MAINTAIN  
ANGLE TOLERANCE

RoHS COMPLIANT

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